



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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Subminiature Radial Leaded, Time-Delay Fuses

SR-5 Series



Radial Leaded Device

Agency Information

- KC: SU05011-9001 3.15A~6.3A, SU05011-9002 1~2.5A, SU05011-9003 40mA~100mA, SU05011-9004 125mA~800mA
- PSE+JET: JET1641-31007-1001 1~5A, JET1641-31007-1002 6.3A
- CCC: 2009010207370507 40mA~4A
- CQC: CQC09012037502 5A, 6.3A
- SEMKO: 1023113 40mA~6.3A
- cURus: Guide JDYX2, File E306920&E19180 and Guide JDYX8, File E306920&E19180
- VDE: File122052, 40020046

Electrical Characteristics								
Rated Current	1.5 x I _n		2.75 x I _n		4 x I _n		10 x I _n	
	min	max	min	max	min	max	min	max
100mA-6.3A	1 hr	2 min	400 mS	10 Sec	150 mS	3 Sec	20 mS	150 mS

Specifications

- Solderability: EIA-186-9E Method 9
- High frequency vibration: MIL-STD-202F, Method 201A
- Operating temperature: -40°C to +125°C
- Soldering heat resistance: 260°C, 10 Sec. max (IEC 60068-2-20)

Description

- Radial leaded time-delay thru-hole fuse
- Designed to IEC 60127-3, Sheet 4
- Internationally accepted for primary and secondary overcurrent protection
- Place directly into PCB or plug into BK/PCS holder
- High inrush withstand capability
- Compatible with leaded and lead-free reflow and wave solder

Ordering

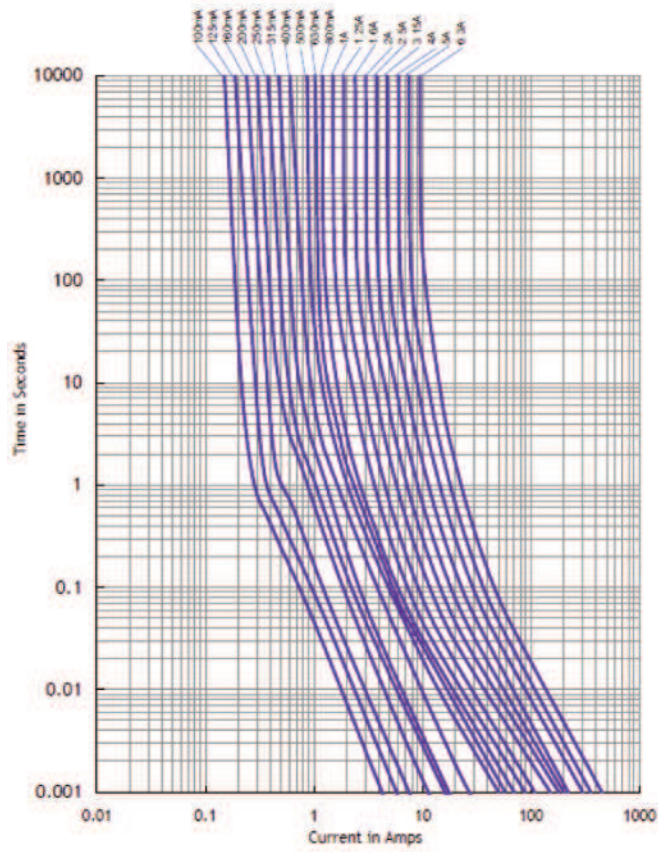
- Specify product and packaging code (i.e., SR-5-1A-AP)

Part Number	Voltage Rating AC	Interrupting Rating (amps) @ Rated Voltage	Typical DC Cold Resistance (Ω)	Typical Melting** I _t (@1mS)	Voltage Drop mV @ 20°C Rated Current	Agency Information					
						VDE	SEMKO	cURus	CCC	KC-Mark	PSE
SR-5-100mA	250	35	2.37	0.015155	288.5	X	X	X	X	X	
SR-5-125mA	250	35	1.6	0.026783	238	X	X	X	X	X	
SR-5-160mA	250	35	1.02	0.039097	196.5	X	X	X	X	X	
SR-5-200mA	250	35	0.94	0.168832	215.5	X	X	X	X	X	
SR-5-250mA	250	35	0.66	0.24778	185	X	X	X	X	X	
SR-5-315mA	250	35	0.43	0.2772	152	X	X	X	X	X	
SR-5-400mA	250	35	0.285	0.771618	127	X	X	X	X	X	
SR-5-500mA	250	35	0.242	2	143.5	X	X	X	X	X	
SR-5-630mA	250	35	0.154	3.5	113	X	X	X	X	X	
SR-5-800mA	250	35	0.112	6.5	104.5	X	X	X	X	X	
SR-5-1A	250	35	0.085	7.5	100	X	X	X	X	X	X
SR-5-1.25A	250	35	0.061	13	91	X	X	X	X	X	X
SR-5-1.6A	250	35	0.043	24	102	X	X	X	X	X	X
SR-5-2A	250	35	0.031	30	74.5	X	X	X	X	X	X
SR-5-2.5A	250	35	0.024	45	72.5	X	X	X	X	X	X
SR-5-3.15A	250	35	0.018	57	70.25	X	X	X	X	X	X
SR-5-4A	250	40	0.012	80	62	X	X	X	X	X	X
*SR-5-5A	250	50	0.010	95.4	57.5	X	X	X	CQC	X	X
*SR-5-6.3A	250	63	0.008	200	60.85	X	X	X	CQC	X	X

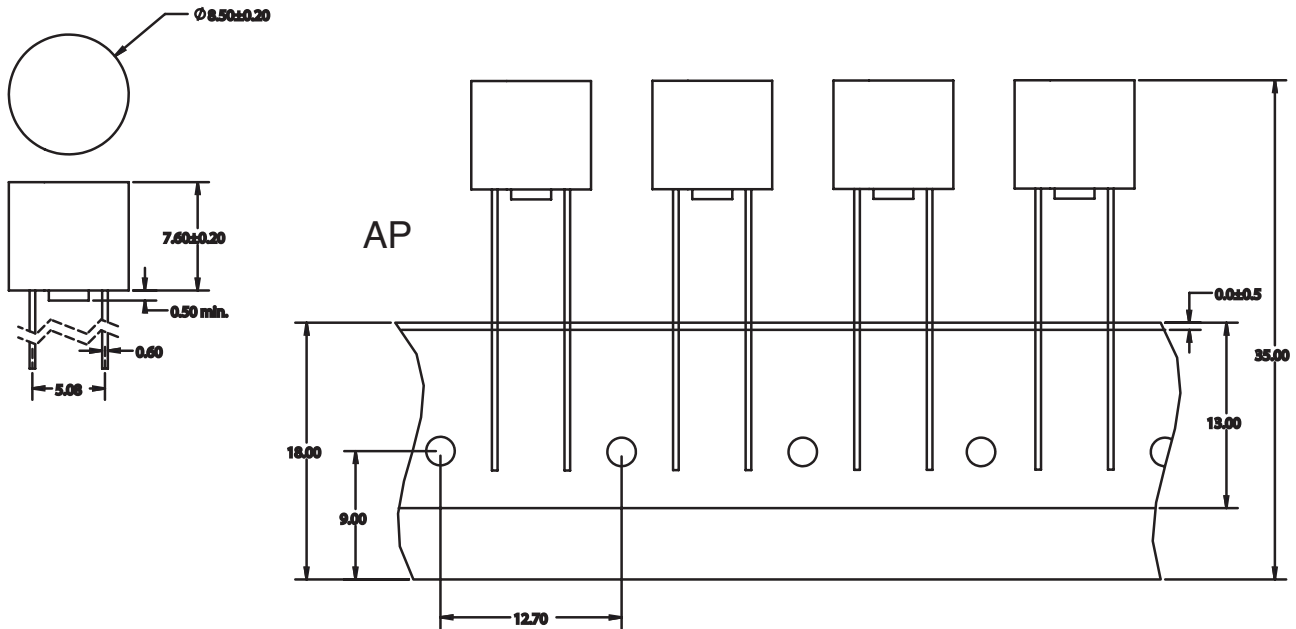
* Conducting Path min. 0.2mm²

** I_t value for 100mA to 400mA is measured at 100I_n. I_t value for 500mA to 6.3A is measured at 10I_n.

Time-Current Curves

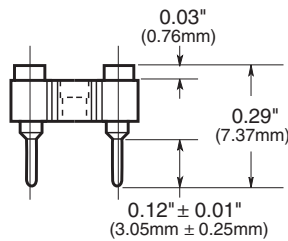
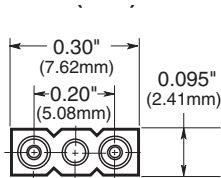


Dimensions – Packaging Information – mm [in]

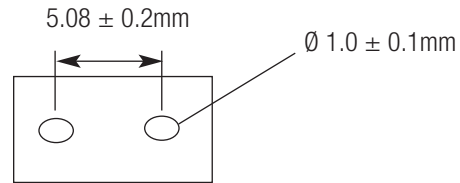


PCS Mounting Socket (RoHS compliant)

- Available as option. Specify catalog number BK/PCS (in bulk 100 per bag)



Land Pattern



Packaging Code	
Packaging Code Suffix	Description
-AP	Ammo-pack taped 1000 per box (see Packaging Information for lead configurations)
-BK, -BK2	In bulk 200 per bag (see Packaging Information for lead configurations)

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